Board Model		CPC508	CPC510	CPC512
Compliance with standards	PICMG 2.0, PICMG 2.1	V	v	
	PICMG 2.30	V	v	
	PICMG cPCI-S.0		v	v
Size, including mezzanines		4HP, 8HP, 12HP	4HP, 5HP*, 8HP, 12HP	4HP, 5HP*, 8HP
CPU		Intel Atom N450, 1,66 GHz Intel Atom D510, 1,66 GHz	Intel i7-3517UE 1,7 GHz Intel i7-3555LE 2,5 GHz Intel i7-3612QE 2,1 GHz	Intel i7-3517UE 1,7 GHz Intel i7-3612LE 2,1 GHz Intel i7-3612QE 2,1 GHz
RAM		1 GB DDR2 SDRAM 667 MHz, soldered	4 or 8 GB DDR3L SDRAM with ECC 1600 MHz, soldered	4 or 8 GB DDR3L SDRAM with ECC 1600 MHz, soldered
Graphics Subsystem	Type	Integrated into CPU	Integrated into CPU	Integrated into CPU
	Interfaces	SVGA, LVDS (18 bit)	2xDisplay Port on the front panel 1xDisplay Port и LVDS (18/24 bit) on MIC590 mezzanine board)	2×Display Port on the front panel
	Number of independend displays	2	3	2
Communications interfaces on the front panel	Gigabit Ethernet	2×Gigabit Ethernet	2×Gigabit Ethernet	2×Gigabit Ethernet
	USB	2×USB 2.0	2×USB 2.0	2×USB 2.0
Storage subsystem interfaces	On the board	1×Compact Flash (Type 2), SATA NAND 4 GB, soldered	1×MicroSD	1×MicroSD
	On mezzanine boards and rear I/O modules	2×SATA II on MIC584	2×SATA II on MIC584	2×SATA III on MIC584

Board Model		CPC508		CPC510	CPC512
Interconnects of inter-module communication by backplane	PCI	32 bit/33 MHz		32-bit, 33 or 66 MHz	No
	PCI Express	Four channels ×1 PCI Express		Two channels ×8 PCI Express (Fat Pipe) Four channels ×4 PCI Express	Two channels×8 PCI Express Gen 3.0 (Fat Pipe) Two channels ×4 PCI Express Gen 3.0 Four channels ×1 PCI Express Gen 2.0
	Gigabit Ethernet	2×Gigabit Ethernet, software-based switching between the front panel and backplane		No	1×Gigabit Ethernet with AMT support
	SATA	2 × SATA I		2 × SATA III 3 × SATA II	2×SATA III 3×SATA II
	USB	4×USB 2.0		8 × USB 2.0 4 × USB 3.0	10×USB 2.0 4×USB 3.0
Support of OS		FreeDOS; Windows XPe; Linux 2.6; QNX 6.5		Windows 7; Linux 2.6	Windows 7 Embedded; Linux 2.6
Energy target*		from 14 to 15,5 W depending on the version		From 30 to 65 W depending on the version	From 30 to 65 W depending on the version
Vibration/Single shock resistance		5g/100g		5g/100g	5g/100g
MTBF (GOST 15150-69)		More than 140000 hours		More than 100000 hours	more than 100 000 hours
Operating temperature range**		-40 ... +85 °C / -50 ... +85 °C		0 ... +70 °C / -40 ... +85 °C	0…+55 °C /0…+70 °C /–40…+85°C
Mezzanine boards	Model	MIC584	MIC589	MIC584	MIC584
	Interfaces on the front panel	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2	2×CAN2.0 (with insulation up to 1000 V); 2×USB 2.0, 2×RS-485/422 (with insulation up to 1000 V)	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2

Board Model		CPC508		CPC510	CPC512
	Interfaces on the board	2×SATA II, 5×RS-232/485, LPT	J2 connector: microphone input, line input/output; 2×CAN2.0; 2×RS-485/422; 2×RS-232; LVDS	2×SATA II, 5×RS-232/485, LPT	2×SATA II, 5×RS-232/485, LPT

***Version with conduction heat removal**

****Operating temperature range depends on the device version**

Target power consumption - is a power consumption for calculation of the system of heat-removal from the module.

Actual power consumption depends on the load and the executed application and can be less than the specified value.